

MMBZxVCL; MMBZxVDL series

Double ESD protection diodes for transient overvoltage suppression

Rev. 01 — 3 September 2008

Product data sheet

1. Product profile

1.1 General description

Unidirectional double ElectroStatic Discharge (ESD) protection diodes in a common cathode configuration, encapsulated in a SOT23 (TO-236AB) small Surface-Mounted Device (SMD) plastic package. The devices are designed for ESD and transient overvoltage protection of up to two signal lines.

Table 1. Product overview

Type number ^[1]	Package		Configuration
	NXP	JEDEC	
MMBZ12VDL	SOT23	TO-236AB	dual common cathode
MMBZ15VDL			
MMBZ18VCL			
MMBZ20VCL			
MMBZ27VCL			
MMBZ33VCL			

[1] All types available as /DG halogen-free version.

1.2 Features

- Unidirectional ESD protection of two lines
- Bidirectional ESD protection of one line
- Low diode capacitance: $C_d \leq 140$ pF
- Rated peak pulse power: $P_{PPM} \leq 40$ W
- Ultra low leakage current: $I_{RM} \leq 5$ nA
- ESD protection up to 30 kV (contact discharge)
- IEC 61000-4-2; level 4 (ESD)
- IEC 61643-321
- AEC-Q101 qualified

1.3 Applications

- Computers and peripherals
- Audio and video equipment
- Cellular handsets and accessories
- Automotive electronic control units
- Portable electronics

1.4 Quick reference data

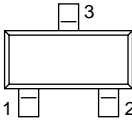
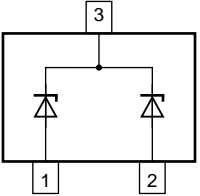
Table 2. Quick reference data

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per diode						
V_{RWM}	reverse standoff voltage					
	MMBZ12VDL MMBZ12VDL/DG		-	-	8.5	V
	MMBZ15VDL MMBZ15VDL/DG		-	-	12.8	V
	MMBZ18VCL MMBZ18VCL/DG		-	-	14.5	V
	MMBZ20VCL MMBZ20VCL/DG		-	-	17	V
	MMBZ27VCL MMBZ27VCL/DG		-	-	22	V
	MMBZ33VCL MMBZ33VCL/DG		-	-	26	V
	C_d	diode capacitance	$f = 1\text{ MHz}; V_R = 0\text{ V}$			
MMBZ12VDL MMBZ12VDL/DG			-	110	140	pF
MMBZ15VDL MMBZ15VDL/DG			-	85	105	pF
MMBZ18VCL MMBZ18VCL/DG			-	70	90	pF
MMBZ20VCL MMBZ20VCL/DG			-	65	80	pF
MMBZ27VCL MMBZ27VCL/DG			-	48	60	pF
MMBZ33VCL MMBZ33VCL/DG			-	45	55	pF

2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	anode (diode 1)		 <p style="text-align: center;">006aaa150</p>
2	anode (diode 2)		
3	common cathode		

3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
MMBZ12VDL	-	plastic surface-mounted package; 3 leads	SOT23
MMBZ15VDL			
MMBZ18VCL			
MMBZ20VCL			
MMBZ27VCL			
MMBZ33VCL			
MMBZ12VDL/DG	-	plastic surface-mounted package; 3 leads	SOT23
MMBZ15VDL/DG			
MMBZ18VCL/DG			
MMBZ20VCL/DG			
MMBZ27VCL/DG			
MMBZ33VCL/DG			

4. Marking

Table 5. Marking codes

Type number	Marking code ^[1]	Type number	Marking code ^[1]
MMBZ12VDL	*MA	MMBZ12VDL/DG	TJ*
MMBZ15VDL	*MB	MMBZ15VDL/DG	TL*
MMBZ18VCL	*MC	MMBZ18VCL/DG	TN*
MMBZ20VCL	*MD	MMBZ20VCL/DG	TQ*
MMBZ27VCL	*ME	MMBZ27VCL/DG	TS*
MMBZ33VCL	*MF	MMBZ33VCL/DG	TU*

- [1] * = -: made in Hong Kong
 * = p: made in Hong Kong
 * = t: made in Malaysia
 * = W: made in China

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
Per diode					
P_{PPM}	rated peak pulse power	$t_p = 10/1000 \mu s$	[1][2] -	40	W
I_{PPM}	rated peak pulse current	$t_p = 10/1000 \mu s$	[1][2]		
	MMBZ12VDL MMBZ12VDL/DG		-	2.35	A
	MMBZ15VDL MMBZ15VDL/DG		-	1.9	A
	MMBZ18VCL MMBZ18VCL/DG		-	1.6	A
	MMBZ20VCL MMBZ20VCL/DG		-	1.4	A
	MMBZ27VCL MMBZ27VCL/DG		-	1	A
	MMBZ33VCL MMBZ33VCL/DG		-	0.87	A
Per device					
P_{tot}	total power dissipation	$T_{amb} \leq 25 \text{ }^\circ\text{C}$	[3] -	350	mW
			[4] -	440	mW
T_j	junction temperature		-	150	$^\circ\text{C}$
T_{amb}	ambient temperature		-55	+150	$^\circ\text{C}$
T_{stg}	storage temperature		-65	+150	$^\circ\text{C}$

[1] In accordance with IEC 61643-321 (10/1000 μs current waveform).

[2] Measured from pin 1 or 2 to pin 3.

[3] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

Table 7. ESD maximum ratings

$T_{amb} = 25 \text{ }^\circ\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Max	Unit
Per diode					
V_{ESD}	electrostatic discharge voltage		[1][2]		
		IEC 61000-4-2 (contact discharge)	-	30	kV
		machine model	-	2	kV

[1] Device stressed with ten non-repetitive ESD pulses.

[2] Measured from pin 1 or 2 to pin 3.

Table 8. ESD standards compliance

Standard	Conditions
Per diode	
IEC 61000-4-2; level 4 (ESD)	> 15 kV (air); > 8 kV (contact)
MIL-STD-883; class 3 (human body model)	> 8 kV

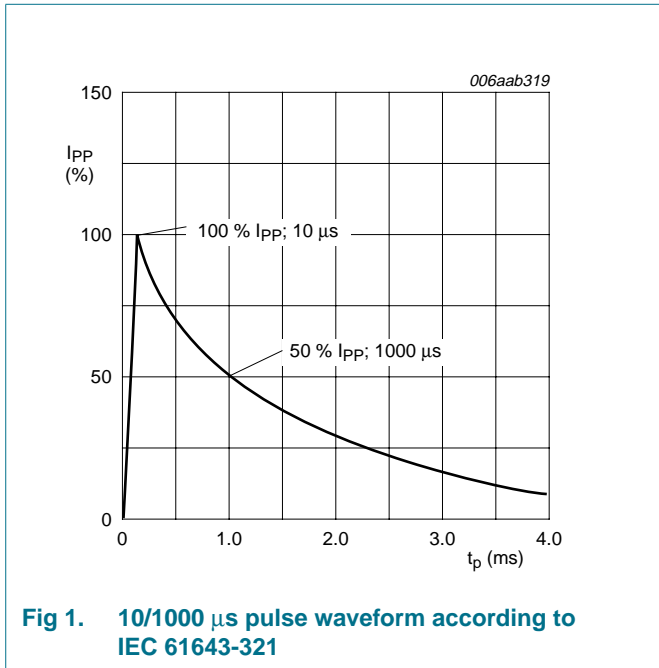


Fig 1. 10/1000 μs pulse waveform according to IEC 61643-321

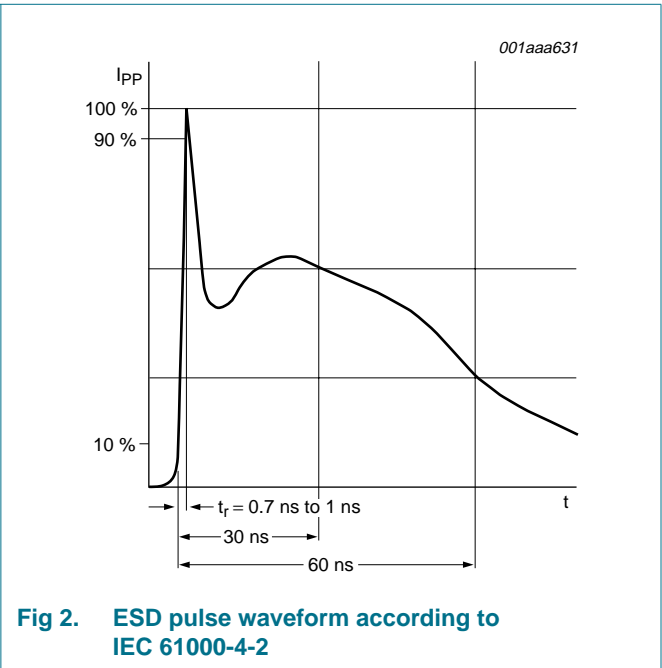


Fig 2. ESD pulse waveform according to IEC 61000-4-2

6. Thermal characteristics

Table 9. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per device						
R _{th(j-a)}	thermal resistance from junction to ambient	in free air	[1]	-	-	350 K/W
			[2]	-	-	280 K/W
R _{th(j-sp)}	thermal resistance from junction to solder point		[3]	-	-	60 K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

[3] Soldering point at pin 3.

7. Characteristics

Table 10. Characteristics
T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per diode						
V _F	forward voltage					
	MMBZ12VDL MMBZ12VDL/DG	I _F = 10 mA	-	-	0.9	V
	MMBZ15VDL MMBZ15VDL/DG	I _F = 10 mA	-	-	0.9	V
	MMBZ18VCL MMBZ18VCL/DG	I _F = 10 mA	-	-	0.9	V
	MMBZ20VCL MMBZ20VCL/DG	I _F = 10 mA	-	-	0.9	V
	MMBZ27VCL MMBZ27VCL/DG	I _F = 200 mA	-	-	1.1	V
	MMBZ33VCL MMBZ33VCL/DG	I _F = 10 mA	-	-	0.9	V
V _{RWM}	reverse standoff voltage					
	MMBZ12VDL MMBZ12VDL/DG		-	-	8.5	V
	MMBZ15VDL MMBZ15VDL/DG		-	-	12.8	V
	MMBZ18VCL MMBZ18VCL/DG		-	-	14.5	V
	MMBZ20VCL MMBZ20VCL/DG		-	-	17	V
	MMBZ27VCL MMBZ27VCL/DG		-	-	22	V
	MMBZ33VCL MMBZ33VCL/DG		-	-	26	V
I _{RM}	reverse leakage current					
	MMBZ12VDL MMBZ12VDL/DG	V _{RWM} = 8.5 V	-	0.1	5	nA
	MMBZ15VDL MMBZ15VDL/DG	V _{RWM} = 12.8 V	-	0.1	5	nA
	MMBZ18VCL MMBZ18VCL/DG	V _{RWM} = 14.5 V	-	0.1	5	nA
	MMBZ20VCL MMBZ20VCL/DG	V _{RWM} = 17 V	-	0.1	5	nA
	MMBZ27VCL MMBZ27VCL/DG	V _{RWM} = 22 V	-	0.1	5	nA
	MMBZ33VCL MMBZ33VCL/DG	V _{RWM} = 26 V	-	0.1	5	nA

Table 10. Characteristics ...continued

 $T_{amb} = 25^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{BR}	breakdown voltage	$I_R = 1\text{ mA}$				
	MMBZ12VDL MMBZ12VDL/DG		11.4	12	12.6	V
	MMBZ15VDL MMBZ15VDL/DG		14.3	15	15.8	V
	MMBZ18VCL MMBZ18VCL/DG		17.1	18	18.9	V
	MMBZ20VCL MMBZ20VCL/DG		19	20	21	V
	MMBZ27VCL MMBZ27VCL/DG		25.65	27	28.35	V
	MMBZ33VCL MMBZ33VCL/DG		31.35	33	34.65	V
C_d	diode capacitance	$f = 1\text{ MHz}; V_R = 0\text{ V}$				
	MMBZ12VDL MMBZ12VDL/DG		-	110	140	pF
	MMBZ15VDL MMBZ15VDL/DG		-	85	105	pF
	MMBZ18VCL MMBZ18VCL/DG		-	70	90	pF
	MMBZ20VCL MMBZ20VCL/DG		-	65	80	pF
	MMBZ27VCL MMBZ27VCL/DG		-	48	60	pF
	MMBZ33VCL MMBZ33VCL/DG		-	45	55	pF
V_{CL}	clamping voltage					[1][2]
	MMBZ12VDL MMBZ12VDL/DG	$I_{PPM} = 2.35\text{ A}$	-	-	17	V
	MMBZ15VDL MMBZ15VDL/DG	$I_{PPM} = 1.9\text{ A}$	-	-	21.2	V
	MMBZ18VCL MMBZ18VCL/DG	$I_{PPM} = 1.6\text{ A}$	-	-	25	V
	MMBZ20VCL MMBZ20VCL/DG	$I_{PPM} = 1.4\text{ A}$	-	-	28	V
	MMBZ27VCL MMBZ27VCL/DG	$I_{PPM} = 1\text{ A}$	-	-	38	V
	MMBZ33VCL MMBZ33VCL/DG	$I_{PPM} = 0.87\text{ A}$	-	-	46	V

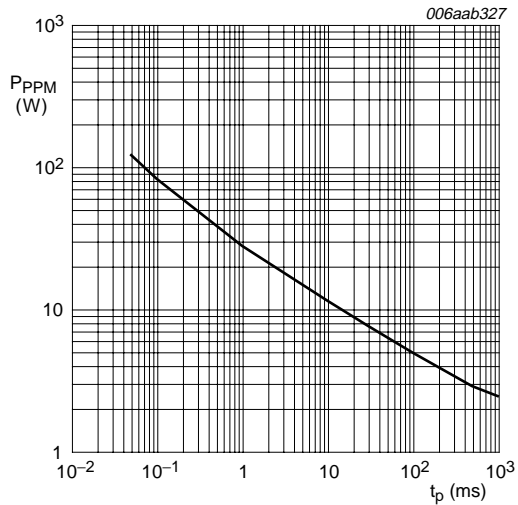
Table 10. Characteristics ...continued

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
S_Z	temperature coefficient	$I_Z = 1\text{ mA}$				
	MMBZ12VDL MMBZ12VDL/DG		-	8.1	-	mV/K
	MMBZ15VDL MMBZ15VDL/DG		-	11	-	mV/K
	MMBZ18VCL MMBZ18VCL/DG		-	14	-	mV/K
	MMBZ20VCL MMBZ20VCL/DG		-	15.8	-	mV/K
	MMBZ27VCL MMBZ27VCL/DG		-	23	-	mV/K
	MMBZ33VCL MMBZ33VCL/DG		-	29.4	-	mV/K

[1] In accordance with IEC 61643-321 (10/1000 μs current waveform).

[2] Measured from pin 1 or 2 to pin 3.



MMBZ27VCL: unidirectional and bidirectional
 $T_{amb} = 25\text{ }^{\circ}\text{C}$

Fig 3. Rated peak pulse power as a function of exponential pulse duration (rectangular waveform); typical values

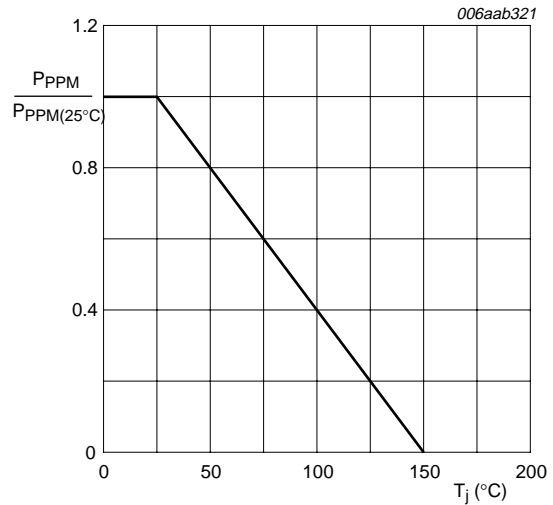
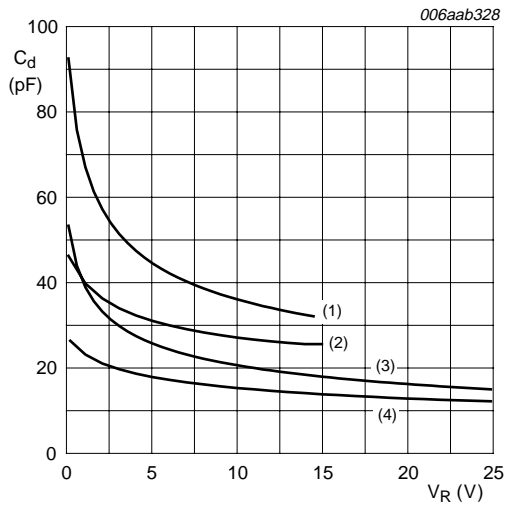
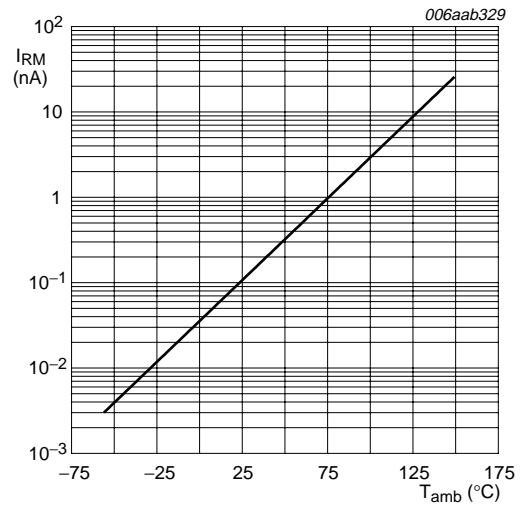


Fig 4. Relative variation of rated peak pulse power as a function of junction temperature; typical values



$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$
 (1) MMBZ15VDL: unidirectional
 (2) MMBZ15VDL: bidirectional
 (3) MMBZ27VCL: unidirectional
 (4) MMBZ27VCL: bidirectional

Fig 5. Diode capacitance as a function of reverse voltage; typical values



MMBZ27VCL: $V_{\text{RWM}} = 22 \text{ V}$

Fig 6. Reverse leakage current as a function of junction temperature; typical values

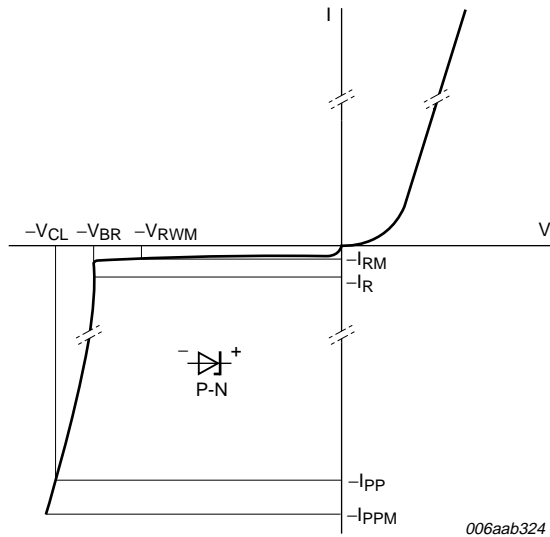


Fig 7. V-I characteristics for a unidirectional ESD protection diode

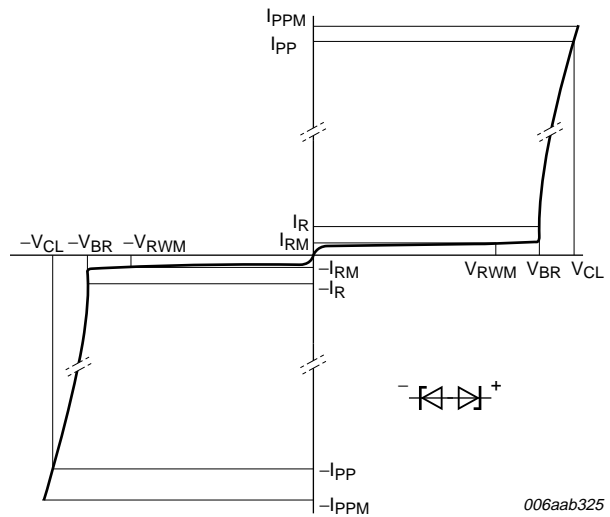


Fig 8. V-I characteristics for a bidirectional ESD protection diode

8. Application information

The MMBZxVCL series and the MMBZxVDL series are designed for the protection of up to two unidirectional data or signal lines from the damage caused by ESD and surge pulses. The devices may be used on lines where the signal polarities are either positive or negative with respect to ground. The devices provide a surge capability of 40 W per line for a 10/1000 μ s waveform.

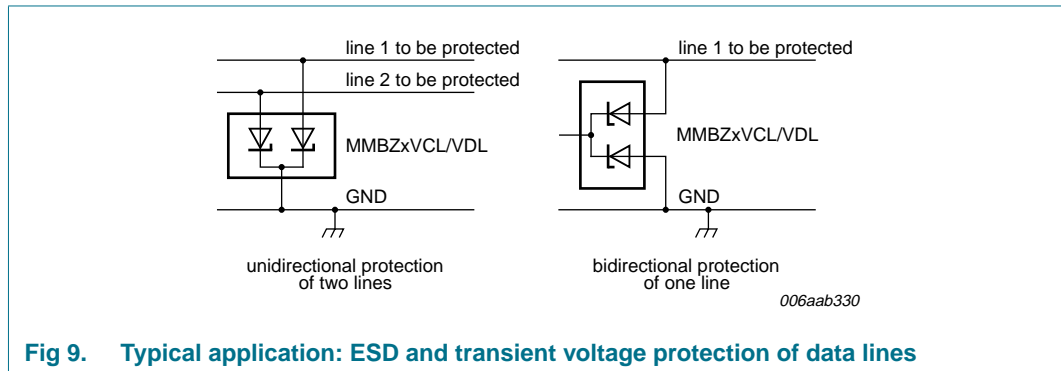


Fig 9. Typical application: ESD and transient voltage protection of data lines

Circuit board layout and protection device placement

Circuit board layout is critical for the suppression of ESD, Electrical Fast Transient (EFT) and surge transients. The following guidelines are recommended:

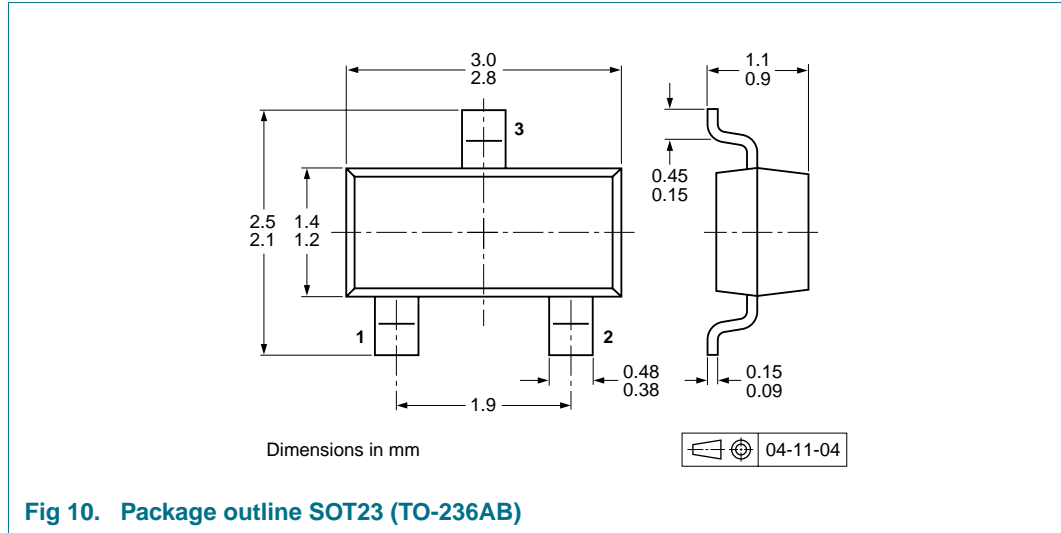
1. Place the devices as close to the input terminal or connector as possible.
2. The path length between the device and the protected line should be minimized.
3. Keep parallel signal paths to a minimum.
4. Avoid running protected conductors in parallel with unprotected conductors.
5. Minimize all Printed-Circuit Board (PCB) conductive loops including power and ground loops.
6. Minimize the length of the transient return path to ground.
7. Avoid using shared transient return paths to a common ground point.
8. Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

9. Test information

9.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

10. Package outline



11. Packing information

Table 11. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity	
			3000	10000
MMBZ12VDL	SOT23	4 mm pitch, 8 mm tape and reel	-215	-235
MMBZ15VDL				
MMBZ18VCL				
MMBZ20VCL				
MMBZ27VCL				
MMBZ33VCL				
MMBZ12VDL/DG	SOT23	4 mm pitch, 8 mm tape and reel	-215	-235
MMBZ15VDL/DG				
MMBZ18VCL/DG				
MMBZ20VCL/DG				
MMBZ27VCL/DG				
MMBZ33VCL/DG				

[1] For further information and the availability of packing methods, see [Section 15](#).

12. Soldering

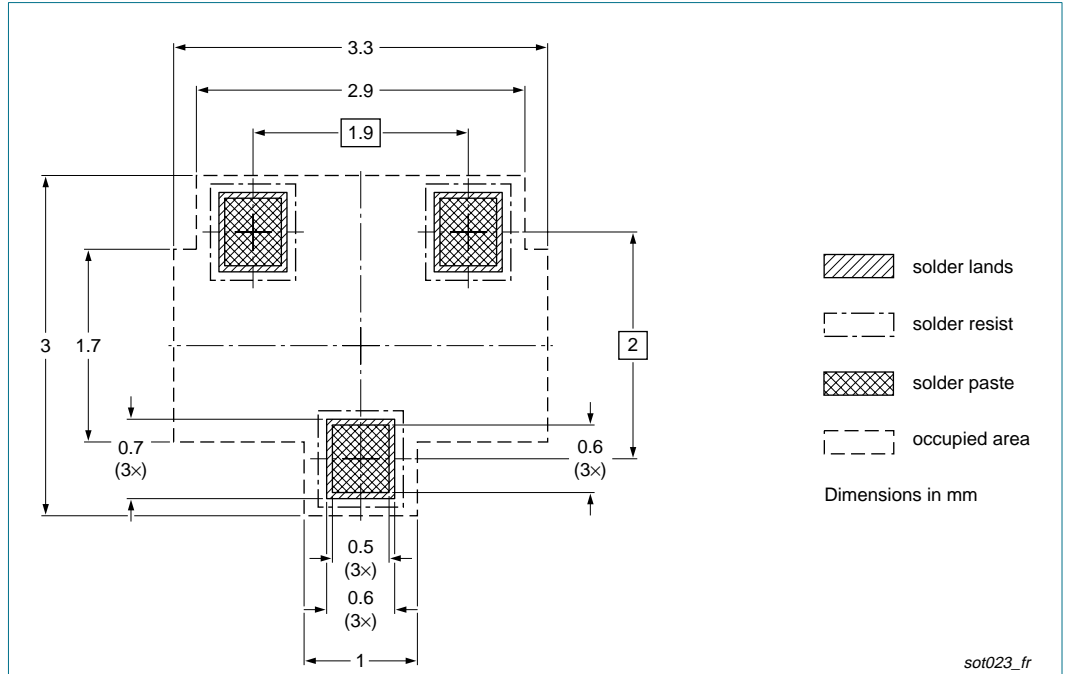


Fig 11. Reflow soldering footprint SOT23 (TO-236AB)

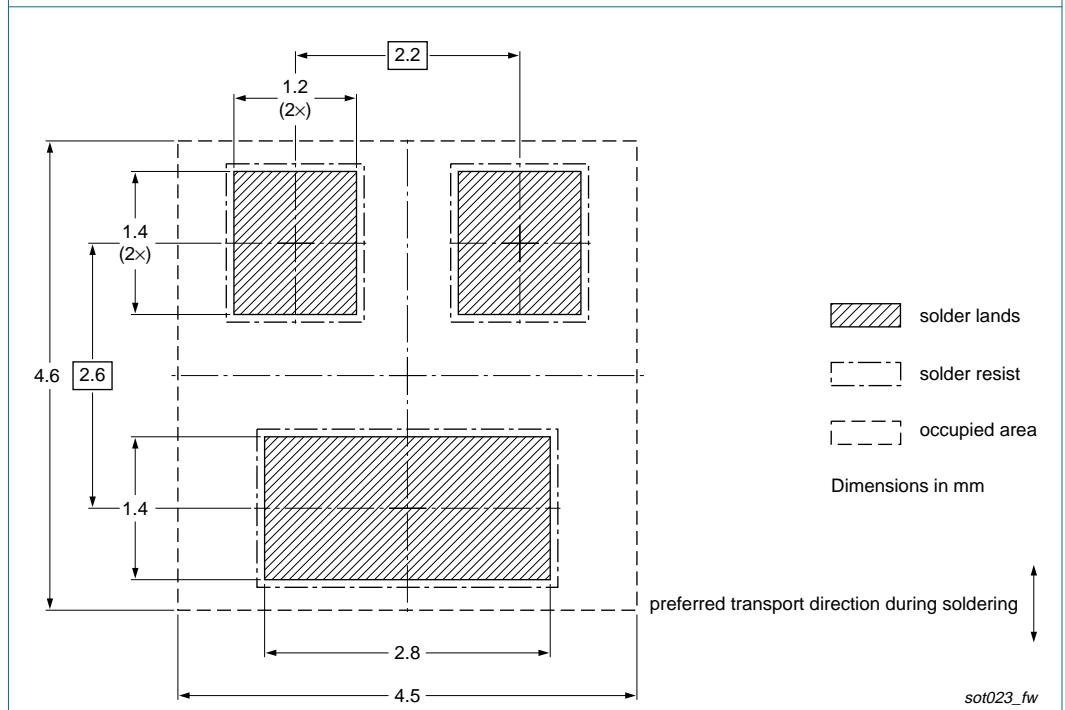


Fig 12. Wave soldering footprint SOT23 (TO-236AB)

13. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
MMBZXVCL_MMBZXVDL_SER_1	20080903	Product data sheet	-	-

14. Legal information

14.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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